

L Number	Hits	Search Text	DB	Time stamp
1	708	257/738.ccls. and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:33
2	355	(257/738.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:33
3	604	257/780.ccls. and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:40
4	258	(257/780.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:48
5	161	((257/780.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)) not ((257/738.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:33
6	1	6285085.URPN.	USPAT	2003/01/01 19:38
7	1087	257/778.ccls. and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 20:01
8	484	(257/778.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:40
9	407	((257/778.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)) not ((257/780.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:41
10	285	((257/778.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)) not ((257/780.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)) and ball\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:50
11	194	((257/778.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)) not ((257/780.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3)) and ball\$2) not ((257/738.ccls. and (@ad<20000428)) and (encapsulat\$3 or mold\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:48
12	0	6323551.URPN.	USPAT	2003/01/01 19:44
13	0	6323551.URPN.	USPAT	2003/01/01 19:44
14	0	6323551.URPN.	USPAT	2003/01/01 19:44
15	4	("5157480" "5668405" "5739585" "5894107").PN.	USPAT	2003/01/01 19:44
16	1723	((chip or die) with post\$2) and (encapsulat\$3 or mold\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:55
17	350	((chip or die) with post\$2) and (encapsulat\$3 or mold\$3)) and ball\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:52

19	0	(((((chip or die) with post\$2) and (encapsulat\$3 or mold\$3)) and ball\$2) and (micrometer\$2 or nm or angstrom)) and (past with (micrometer\$2 or nm or angstrom))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:54
18	67	(((((chip or die) with post\$2) and (encapsulat\$3 or mold\$3)) and ball\$2) and (micrometer\$2 or nm or angstrom))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:54
20	9633	((chip or die) with (pad or post\$2)) and (encapsulat\$3 or mold\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 19:58
21	1945	((chip or die) with (pad or post\$2)) and (encapsulat\$3 or mold\$3)) and ((peripher\$2 or edge) with (pad or post\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 20:01
22	289	((chip or die) with (pad or post\$2)) and (encapsulat\$3 or mold\$3)) and ((peripher\$2 or edge) near (pad or post\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 20:01
23	197	(((((chip or die) with (pad or post\$2)) and (encapsulat\$3 or mold\$3)) and ((peripher\$2 or edge) near (pad or post\$2))) and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/01 20:02